

HSD8Dxxx Series

Unidirectional TVS Diodes

DESCRIPTION

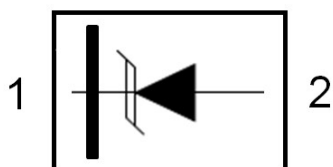
The HSD8Dxxx Series is designed for applications requiring transient overvoltage protection capability. They are intended for use in voltage and ESD sensitive equipment such as computers, printers, business machines, communication systems, medical equipment and other applications. These devices are ideal for situations where board space is at a premium.

This series has been specifically designed to protect sensitive components which are connected to power, data and transmission lines from overvoltage caused by ESD (electrostatic discharge), CDE (Cable Discharge Events), and EFT (electrical fast transients).

ORDERING INFORMATION

- ✧ Device: HSD8Dxxx
- ✧ Package: DFN1006
- ✧ Material: RoHS compliant & Halogen free
- ✧ Packing: Tape & Reel
- ✧ Quantity per reel: 10,000pcs

PIN CONFIGURATION



FEATURES

- ✧ IEC61000-4-2 (ESD) $\pm 30\text{kV}$ (Contact)
 $\pm 30\text{kV}$ (Air)
- ✧ IEC61000-4-4 (EFT) 40A (5/50ns)
- ✧ 350 Watts Peak Pulse Power per (tp=8/20μs)
- ✧ Protects one I/O line (unidirectional)
- ✧ Low clamping voltage
- ✧ Working voltages: 3.3V to 36V
- ✧ Low leakage current

MECHANICAL DATA

- ✧ DFN1006 package
- ✧ Flammability Rating: UL 94V-0
- ✧ Packaging: Tape and Reel
- ✧ High temperature soldering guaranteed:
260°C/10s
- ✧ Reel size: 7 inch

APPLICATIONS

- ✧ Cell Phone Handsets and Accessories
- ✧ Microprocessor based equipment
- ✧ Personal Digital Assistants (PDA's)
- ✧ Notebooks, Desktops, and Servers
- ✧ Portable Instrumentation
- ✧ Networking and Telecom
- ✧ Serial and Parallel Ports
- ✧ Peripherals

PACKAGE OUTLINE



ABSOLUTE MAXIMUM RATING

Symbol	Parameter	Value	Units
V_{ESD}	ESD per IEC 61000-4-2 (Contact) ESD per IEC 61000-4-2 (Air)	± 30 ± 30	kV
P_{PP}	Peak Pulse Power (8/20 μ s)	350	W
T_{OPT}	Operating Temperature	-55/+150	°C
T_{STG}	Storage Temperature	-55/+150	°C
T_L	Lead Soldering Temperature	260 (10 sec.)	°C

ELECTRICAL CHARACTERISTICS ($T_{amb}=25^{\circ}C$)

PART NUMBER	DEVICE MARKING	V _{RWM} (V) (max.)	V _B (V) (min.)	I _T (mA)	V _C @1A (V) (max.)	V _C (V) (max.) (@A)		I _R (μA) (max.)	C _T (pF) (max.)
HSD8D3V3	03W	3.3	4	1	6.5	14	20	5	450
HSD8D5V0	05W	5	6	1	9.8	18	17	2	300
HSD8D8V0	08W	8	8.5	1	10.5	24	15	1	240
HSD8D12V	12W	12	13.3	1	19	32	11	1	130
HSD8D15V	15W	15	16.7	1	24	38	10	1	120
HSD8D18V	18W	18	20.0	1	29	45	9	1	100
HSD8D24V	24W	24	26.7	1	43	52	7	1	80
HSD8D36V	36W	36	40	1	60	75	5	1	60

ELECTRICAL CHARACTERISTICS CURVE

Fig 1 8/20 μ s Waveform per IEC61000-4-5

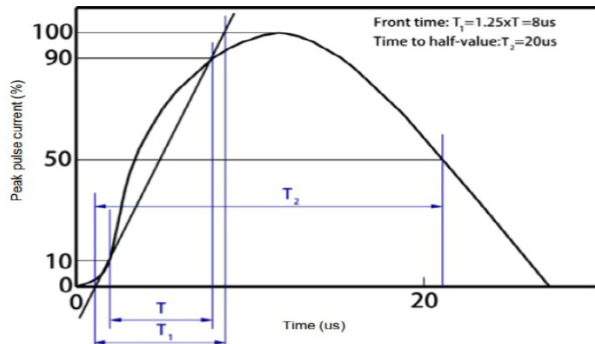


Fig 2 Contact Discharge Current Waveform per IEC 61000-4-2)

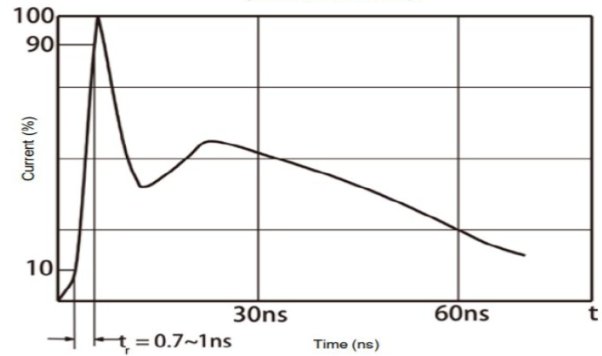


Fig 3 Voltage vs Capacitance

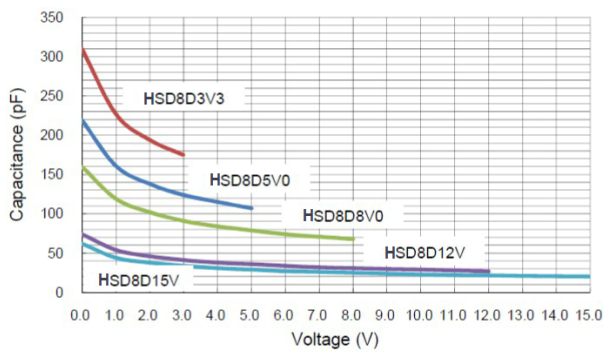


Fig 4 Voltage vs Capacitance

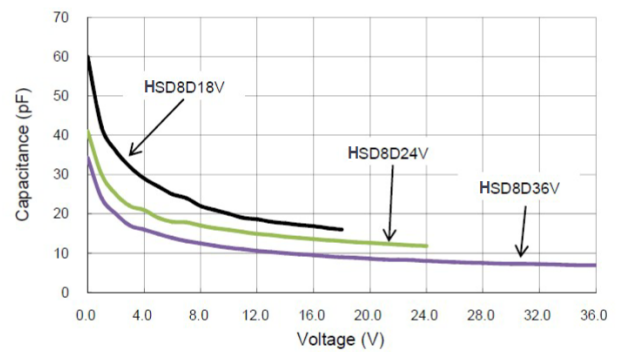


Fig 5 Clamping Voltage vs Peak Pulse Current

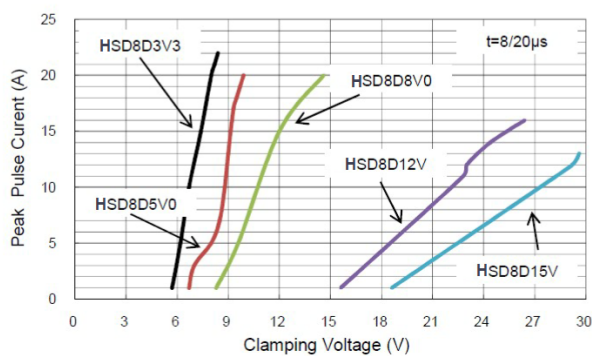
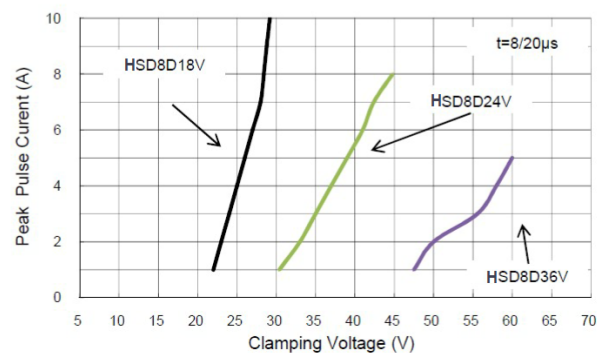
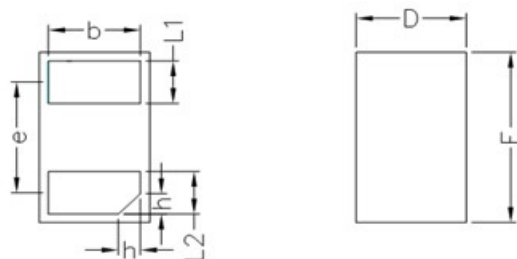


Fig 6 Clamping Voltage vs Peak Pulse Current



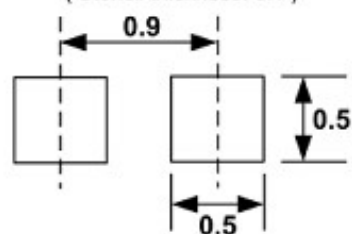
DFN1006 PACKAGE OUTLINE DIMENSIONS



Unit: mm

	MIN	NOM	MAX
D	0.55	0.60	0.65
E	0.95	1.00	1.05
L1	0.20	0.25	0.30
L2	0.20	0.25	0.30
b	0.45	0.50	0.55
e	0.65BSC		
A	0.45	0.50	0.55
h	0.07	0.12	0.17

Dimension: Millimeter
(Stencil thickness: 0.1)



Soldering Footprint